



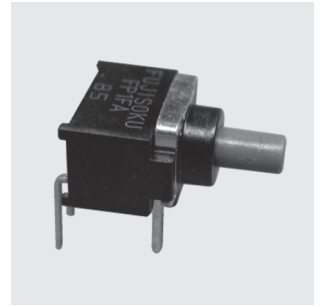
THE DATASHEET OF CFP2-2RC4-AW



CFP2

- Terminal Pins: Straight
- Actuator Color: Gray

Ultra-Miniature Pushbutton Switches



Washable

RoHS Compliant

Features

1. Ultra-miniature pushbutton switch for high density mounting.
2. Washable.
3. Terminal pin pitch: 2.54 mm.
4. Independent detent mechanism ensures light operational feel.
5. Clip contact mechanism for long-term contact reliability.
6. Gold-plated contacts.

Specifications

Rating	Max.	0.4 VA (28 VDC max.)
	Min.	1 μ A 20 mVDC
Initial contact resistance	100 m Ω max. (1.5 mA 200 μ VAC)	
Dielectric strength	250 VAC 1 minute	
Insulation resistance	500 M Ω min. (250 VDC)	
Electrical life	10,000 operations at max.rating 30,000 operations at min.rating	
Mechanical life	30,000 cycles	
Operating force	1.47 \pm 0.98 N	
Operating temperature range	-40~+85 $^{\circ}$ C	
Storage temperature range	-40~+85 $^{\circ}$ C	

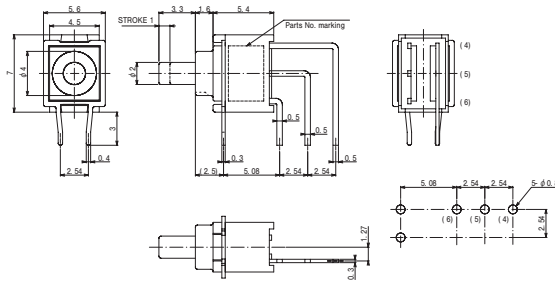
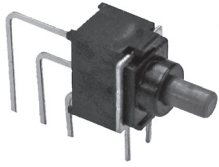
Part Numbering

CFP2		2	R	C4	A	W						
Series Actuator		Number of poles	Switching function	Terminal style	Actuator shape	Packing form						
Code	Type	Fig.	Number of poles	1 pole	2 poles	Switching function	Fig.	Terminal style	Code	Actuator shape	Code	Packing form
P	Pushbutton	1	1 pole	F	R	ON - (ON)	C	PC Straight	A	Standard	W	Tray
		2	2 poles				C4	Right angle				
							C6	Vertical mounting				

Terminal style of c (Style : P/C Terminal)	Terminal style of c4 (Style : R/A Terminal)	Terminal style of c6 (Style : V/M Terminal)

SPDT

V/M



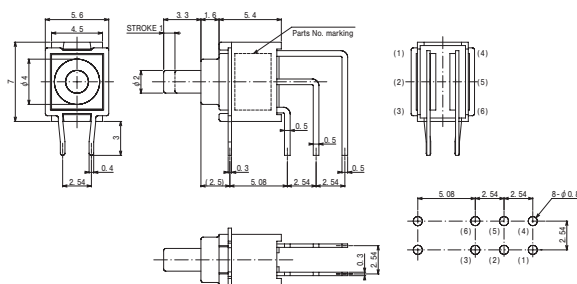
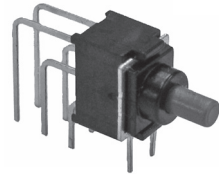
Terminal numbers are not shown on the switch.

(Top view)
PC Hole Layouts

Switching function		
Part No.		
CFP2-1FC6-AW	ON	(ON)
Connecting terminals	5-6	5-4

DPDT

V/M



Terminal numbers are not shown on the switch.

(Top view)
PC Hole Layouts

Switching function		
Part No.		
☆ CFP2-2RC6-AW	ON	(ON)
Connecting terminals	2-3 5-6	2-1 5-4

※ The above pcb hole dimengion, it is a top view drawing when we fix the switch.

Handling Specifications

1. Soldering Specifications

(1)Manual Soldering

Device : Soldering iron
350°C, Max.; 3 seconds, Max.

(2)Auto Soldering

Device : Jet wave type or dip type
260°C, Max.; 3-5 seconds, Max. (One time)

Total dip time: Within 10 seconds

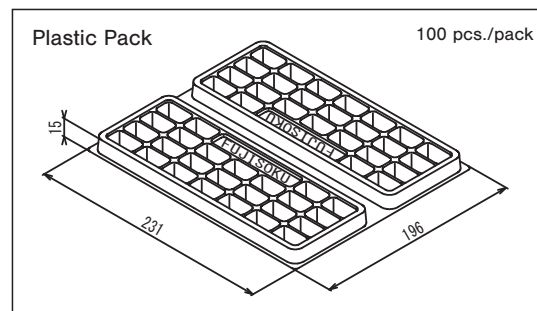
- Pre-heating should be done at temperatures from 80°C to 120°C and within 120 seconds

(3)When soldering two or more terminals to a common land, use solder resist to separate them

2. Flux Cleaning

- (1)Solvents : Fluorine or Alcohol type
- (2)Cleaning after soldering should be done after the PC board is exposed to room temperature (30°C or below) for 1 to 2 hours.
- (3)Do not use ultrasonic cleaning.

Packaging Specifications



(ON) : Momentary.

☆ : Semi-standard products.

Looking for pricing, stock, or lifecycle information?

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